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CONSOLIDATED VERSION

Information technology - Telecommunications bonding networks for buildings
and other structures

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IEC Secretariat
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

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FOREWORD

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In this Redline version, a vertical line in the margin shows where the technical content is modified by amendments 1 and 2. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.

International Standard ISO/IEC 30129 was prepared by subcommittee 25: Interconnection of information technology equipment, of ISO/IEC joint technical committee 1: Information technology.

This International Standard has been approved by vote of the member bodies, and the voting results may be obtained from the address given on the second title page.

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